

U.S. Serial No. 09/501,114

PATENTS

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:)
 Tzeng) Group Art Unit: 1762
 Serial No: 09/501,114) Examiner: Markham, W.
 Filed: February 10, 2000) Docket No.: A029 1080
 For: Method of Plasma Enhanced)
 Chemical Vapor Deposition of)
 Diamond)

#4/3
 Reda
 11/6/01

AMENDMENT A UNDER 37 C.F.R. §1.111

Assistant Commissioner For Patents
 Box Amendment
 Washington, D.C. 20231

FAX RECEIVED
 OCT 24 2001
 GROUP 1700
 OFFICIAL

Dear Sir:

In response to the office action dated July 25, 2001, please amend the subject application as follows.

IN THE SPECIFICATION

On page ⁶~~7~~, starting at line 17, please delete the paragraph and insert in place thereof the following:

The substrate generally is sheet or wafer of silicon, copper, aluminum and molybdenum.

Some of the substrates are polished using 1 μ m diamond paste prior to the deposition process.

Typically, the substrate is mounted on a water cooled substrate holder. The substrate can be either in touch with the plasma or at a distance from the plasma. In experiments using the